









CEK02N7G

700V ▲ 5.75Ω ▲ 0.4A ▲ Si MOSFET

SILICON Si MOSFET ▲ THT type
N-channel enhancement mode
UL94V-0 rated flame retardant epoxy
TO92 package
Ammo tape
Rugged and reliable

MAXIMUM RATINGS

Parameter (T_c = 25°C, unless otherwise noted)		Characteristics
Drain-Source Voltage	V _{DS}	700V
Gate-Source Voltage	V _{GS}	±30V
Continuous Drain Current	I _D	0.4A
Pulsed Drain Current Note 1	I _{DM}	1.6A
Maximum Power Dissipation	P _D	3.1W
Operating and Storage Temperature Range	T _J , T _{STG}	-55°C to +150°C

THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Lead Note 2	R _{TH_JL}	40°C/W

APPLICATIONS

Industrial Inverters	Motors & Drives	Renewable Energy	SMPS	UPS
		*		

PIN DESCRIPTION

Circuit Diagram	Outline • Front View	Pin No.	Description
G (1) S (3)	1 2 3	1 2 3	Gate Drain Source



ELECTRICAL CHARACTERISTICS \blacktriangle T_C = 25°C, unless otherwise noted

Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_D = 250\mu A$	BV_{DSS}	700			V
Zero Gate Voltage Drain Current	$V_{DS} = 700V, V_{GS} = 0V$	I _{DSS}			25	μΑ
Gate Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$	I_{GSSF}			100	nA
Gate Body Leakage Current, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	I_{GSSR}			-100	nA
On Characteristics						
Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250 \mu A$	$V_{GS(th)}$	2		4	V
Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 0.2A$	R _{DS(ON)}		5.75	6.75	Ω
Dynamic Characteristics Note 3						
Input Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1MHz$	C _{ISS}		325		pF
Output Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1MHz$	Coss		70		pF
Reverse Transfer Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1MHz$	C_{RSS}		20		pF
Switching Characteristics Note 3						
Turn-On Delay Time	V_{DD} = 300V, V_{GS} = 10V, I_D = 0.4A, $R_{G(ext)}$ = 18 Ω	t _{D(ON)}		21		ns
Turn-On Rise Time	V_{DD} = 300V, V_{GS} = 10V, I_D = 0.4A, $R_{G(ext)}$ = 18 Ω	t _R		14		ns
Turn-Off Delay Time	V_{DD} = 300V, V_{GS} = 10V, I_D = 0.4A, $R_{G(ext)}$ = 18Ω	t _{D(OFF)}		34		ns
Turn-Off Fall Time	V_{DD} = 300V, V_{GS} = 10V, I_D = 0.4A, $R_{G(ext)}$ = 18Ω	t _F		27		ns
Total Gate Charge	$V_{DS} = 480V$, $V_{GS} = 10V$, $I_{D} = 0.4A$	Q_{G}		12		nC
Gate Source Charge	$V_{DS} = 480V$, $V_{GS} = 10V$, $I_{D} = 0.4A$	Q_{GS}		2		nC
Gate Drain Charge	$V_{DS} = 480V$, $V_{GS} = 10V$, $I_D = 0.4A$	Q_{GD}		7		nC
Drain-Source Diode Characteristics a	nd Maximum Ratings					
Drain-Source Diode Forward Current		I _S			0.4	Α
Drain-Source Diode Forward Voltage Note 2	$V_{GS} = 0V$, $I_S = 0.2A$	V_{SD}			1.5	V

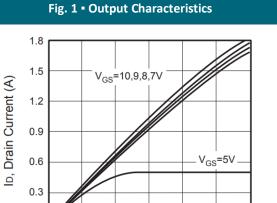
Notes

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature
- 2: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 3: Guaranteed by design, not subject to production testing.



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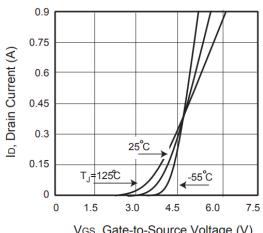
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VDS, Drain-to-Source Voltage (V)

12

Fig. 2 • Transfer Characteristics



Vgs, Gate-to-Source Voltage (V)

Fig. 3 • Capacitance

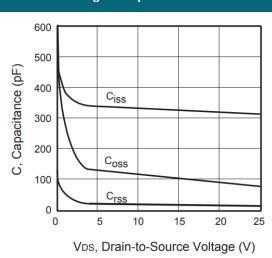


Fig. 4 • On-Resistance Variation with Temperature

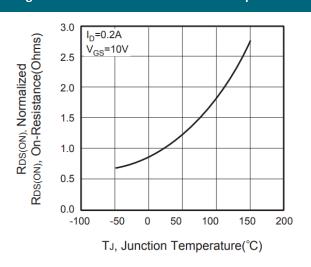


Fig. 5 • Gate Threshold Variation with Temperature

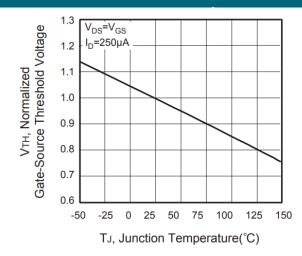
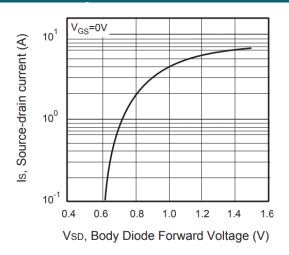


Fig. 6 • Body Diode Forward Voltage Variation with Source Current



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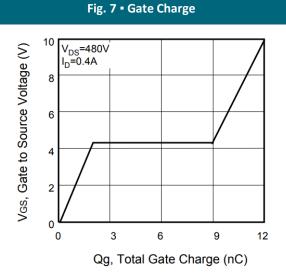


Fig. 8 • Maximum Safe Operating Area

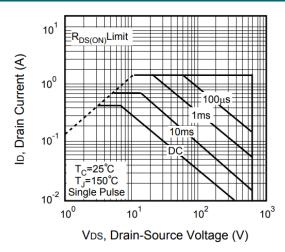
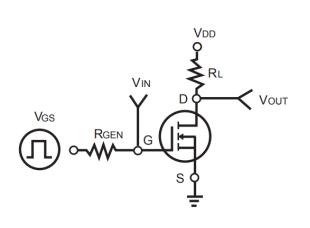


Fig. 9 • Switching Test Circuit

Fig. 10 • Switching Waveforms



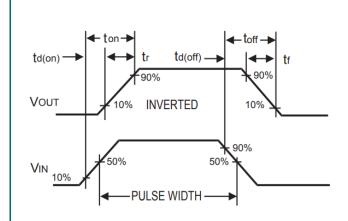
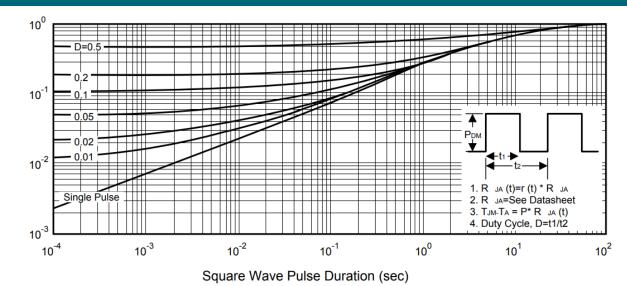


Fig. 11 - Normalized Thermal Transient Impedance Curve

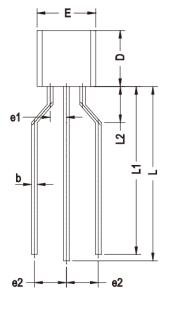




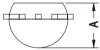
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PACKAGE OUTLINE







Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
Α	3.460	3.660	3.860
b	0.360	0.460	0.560
b1	0.350	0.430	0.510
D	4.380	4.580	4.780
Е	4.430	4.640	4.850

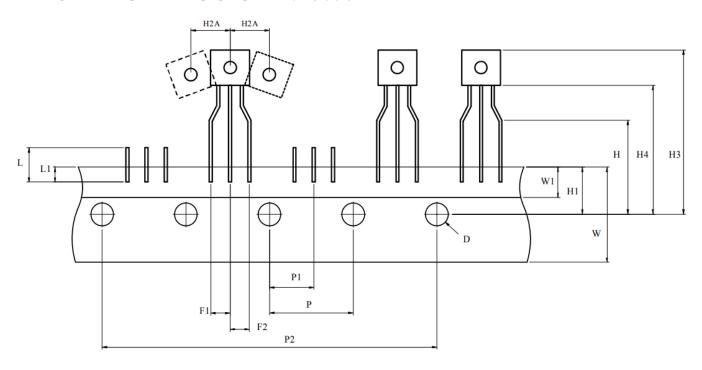
Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)		
e1		1.270 BSC			
e2	2.500 BSC				
L	14.250	14.560	14.870		
L1	12.500	13.500	14.500		
L2	2.800	2.900	3.000		

ORDERING INFORMATION

Part Number	Package	Packing	Ammo Qty.	Inner Box Qty.	Outer Box Qty.
CEK02N7G	TO-92	Ammo Tape	2,000pcs	2,000pcs	32,000pcs



AMMO TAPING DIMENSIONS ▲ All dimensions in mm

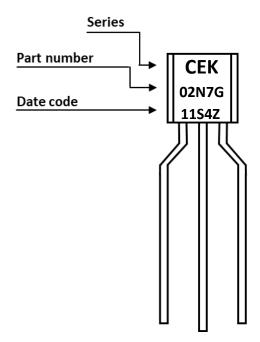


Package	D	F1, F2	F1 – F2	н	H1	H2A	Н3	H4
	4.00	2.50	±0.30	16.00	9.00	0.50	27.00	20.00
	±0.20	+0.20 -0.10	-	±0.50	±0.50	Max.	Max	Max.
TO92	L	L1	Р	P1	P2	W	W1	W2
TO92	L 11.00	L1 2.50	P 12.70	P1 6.35	P2 50.80	W 17.50 ~ 19.00	W1 5.00 ~ 7.00	W2 0.50

Note: All dimensions meet EIA-481-D requirements.

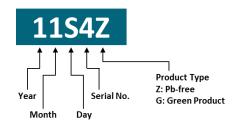


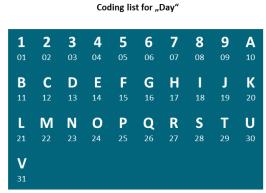
PART MARKING



DATE CODE

Example: 11S4Z

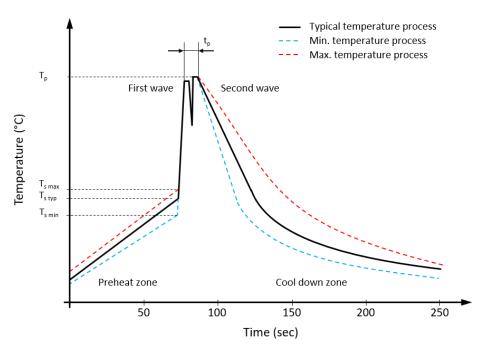








RECOMMENDED WAVE SOLDERING PROFILE A THT PACKAGE



Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

Profile Features		Value ▲ Sn-Pb Assembly	Value ▲ Pb-free Assembly
Preheat temperature min.	$T_{s min}$	100 °C	100 °C
Preheat temperature typical	T _{s typ}	120 °C	120 °C
Preheat temperature max.	T _{s max}	130 °C	130 °C
Preheat time t_s from T_{smin} to T_{smax}	ts	70 seconds	70 seconds
Peak temperature	Tp	235 °C to 260 °C	245 °C to 260 °C
Time of actual peak temperature	t _p	Max. 10 seconds Max. 5 second each wave	Max. 10 seconds Max. 5 second each wave
Ramp-down date min.		~ 2 °C/second	~ 2 °C/second
Ramp-down rate typical		~ 3.5 °C/second	~ 3.5 °C/second
Ramp-down rate max.		~ 5 °C/second	~ 5 °C/second
Time 25°C to 25°C		4 minutes	4 minutes



REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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